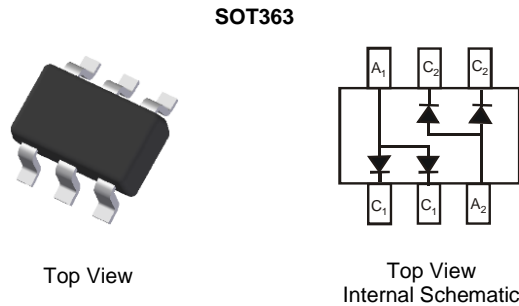


Features

- Fast Switching Speed
- High Reverse Breakdown Voltage
- Low Leakage Current
- Low Capacitance
- For General Purpose Switching Applications
- Two "BAW56" Circuits In One Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Notes 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **An Automotive-Compliant Part is Available Under Separate Datasheet ([BAW56HDWQ](#))**

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208③
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

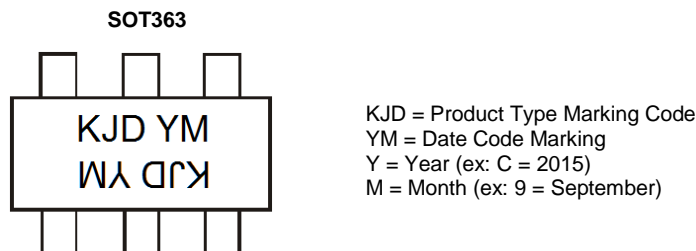


Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BAW56HDW-13	AEC-Q101	SOT363	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022
Code	C	D	E	F	G	H	I	J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	71	V
Forward Continuous Current (Note 5)	I_{FM}	250	mA
Repetitive Peak Forward Current	I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}	@ $t = 1.0\mu\text{s}$	4
		@ $t = 1.0\text{ms}$	1.0
		@ $t = 1.0\text{s}$	0.5
			A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Thermal Resistance Junction to Solder Point	$R_{\theta JSP}$	255	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	100	—	V	$I_R = 2.5\mu\text{A}$
Forward Voltage	V_F	—	0.715	V	$I_F = 1.0\text{mA}$
		—	0.855		$I_F = 10\text{mA}$
		—	1.0		$I_F = 50\text{mA}$
		—	1.25		$I_F = 150\text{mA}$
Reverse Current (Note 6)	I_R	—	0.5	μA	$V_R = 80\text{V}$
		—	50	μA	$V_R = 80\text{V}, T_J = +150^\circ\text{C}$
		—	30	μA	$V_R = 25\text{V}, T_J = +150^\circ\text{C}$
		—	30	nA	$V_R = 25\text{V}$
Total Capacitance	C_T	—	1.5	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{RR}	—	4.0	ns	$I_F = I_R = 10\text{mA}, I_{RR} = 0.1 \times I_R, R_L = 100\Omega$
Forward Recovery Voltage	V_{FR}	—	1.75	V	$I_F = 10\text{mA}, t_R = 20\text{ns}$

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, please see <http://www.diodes.com/package-outlines.html> for the latest version.
6. Short duration pulse test used to minimize self-heating effect.

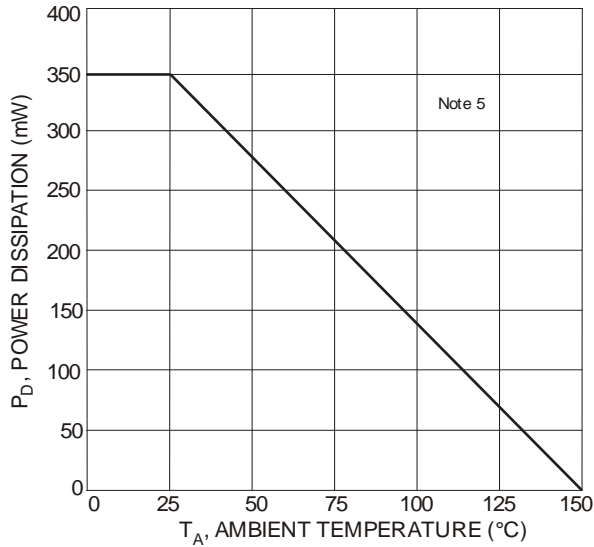


Fig. 1 Power Derating Curve, Total Package

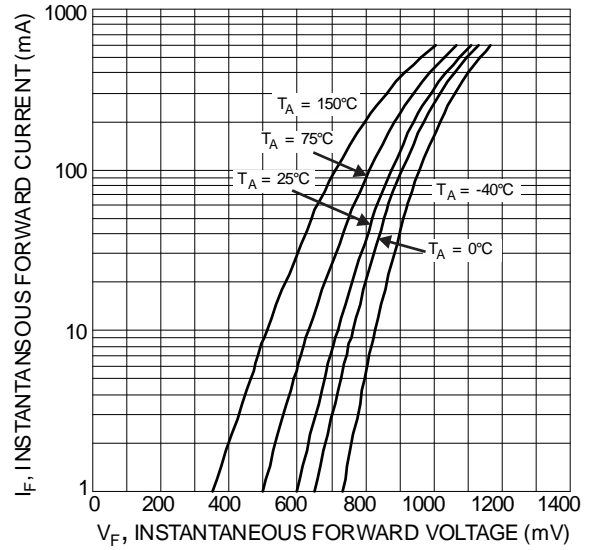


Fig. 2 Typical Forward Characteristics

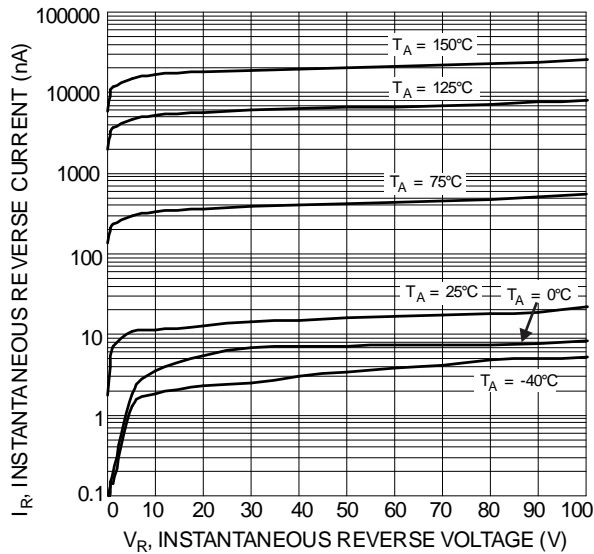


Fig. 3 Typical Reverse Characteristics, Per Element

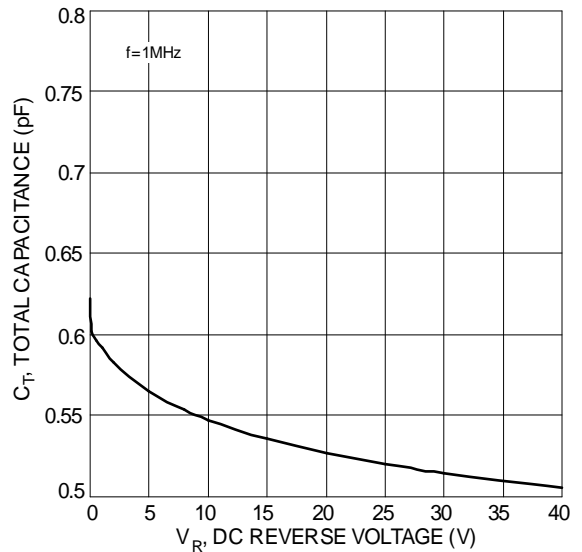
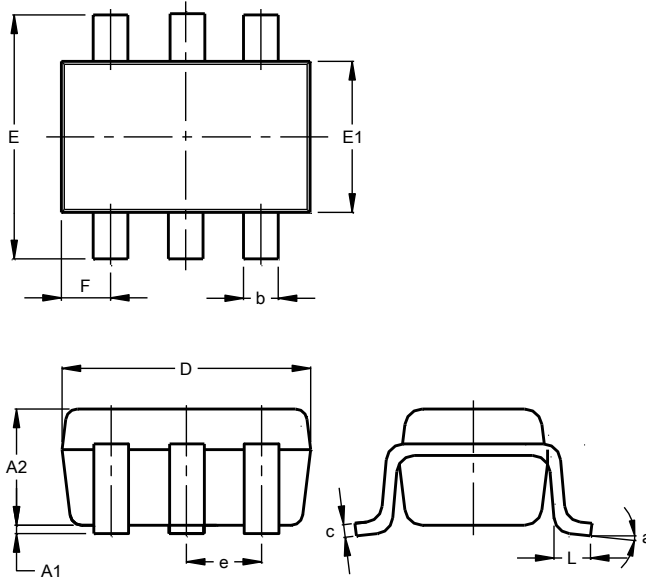


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363

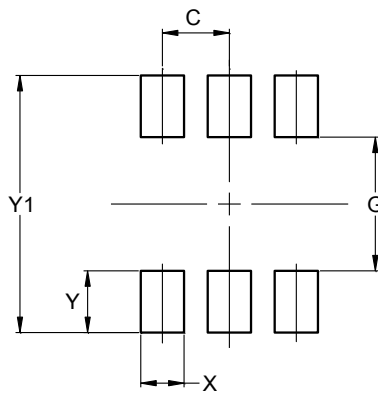


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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